

General Description

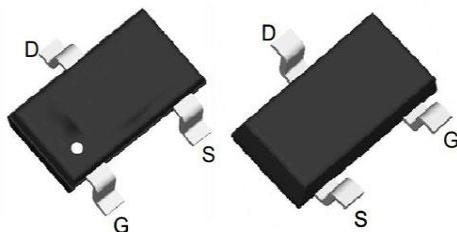
20V /3A Single N Power MOSFET

Very low on-resistance RDS(on) @ VGS=4.5 V

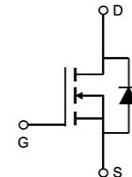
Pb-free lead plating; RoHS compliant

V_{DS}	20	V
R_{DS(on)}, TYP@VGS=10V	43.4	mΩ
R_{DS(on)}, TYP@VGS=4.5	70.0	mΩ
I_D	3	A

Top View



Bottom View



Part ID	Package Type	Marking	Tape and reel infomation
AC2302	SOT23-3	2302	3000

100% UIS Tested
100% RG Tested

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	8	±V
Continuous Drain Current A	I _D	3.0	A
		2.5	
Pulsed Drain Current B	I _{DM}	4.8	
Avalanche Current G	I _{AR}	1.0	
Repetitive avalanche energy L=0.1mH G	E _{AR}	2.2	mJ
Power Dissipation A	P _D	1.4	W
		0.9	
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient A	R _{θJA}	155	232	°C/W
Maximum Junction-to-Ambient A		310	372	°C/W
Maximum Junction-to-Lead c	R _{θJL}	93	148	°C/W

STATIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250\mu A, V_{GS} = 0V$	20			V
Id_{SS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	uA
					5	
I_{GSS}	Gate-Body leakage current	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.8	1	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V, ID=3A$		43.4	62.0	$m\Omega$
		$V_{GS}=2.5V, ID=3A$		70.0	85.0	
g_{FS}	Forward Transconductance	$V_{DS}=5V, ID=3A$		68		S
V_{SD}	Diode Forward Voltage	$IS=1A, V_{GS}=3V$		0.72	1	V
I_S	Maximum Body-Diode Continuous Current				3	A

DYNAMIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V, f=1MHz$		260	317	pF
C_{oss}	Output Capacitance			48	59	pF
C_{rss}	Reverse Transfer Capacitance			27	32	pF
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$			0.3	Ω

SWITCHING PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$Q_g(10V)$	Total Gate Charge	$V_{GS}=10V, V_{DS}=15V, ID=3A$		2.9		nC
$Q_g 4.5V)$	Total Gate Charge			1.45		
Q_{gs}	Gate Source Charge			0.42		
Q_{gd}	Gate Drain Charge			0.6		
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DS}=15V, RL=0.75\Omega, R_{GEN}=3\Omega$		7		ns
t_r	Turn-On Rise Time			5.6		
$t_{D(off)}$	Turn-Off Delay Time			19.6		
t_f	Turn-Off Fall Time			6.3		
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-8A, dI/dt=500A/\mu s$		14		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=18A, dI/dt=500A/\mu s$		3.8		nC

ELECTRICAL AND THERMAL CHARACTERISTICS

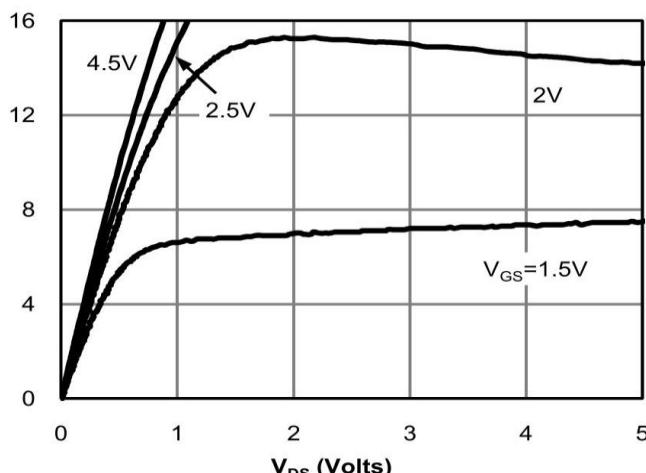


Figure 1: On-Region Characteristics

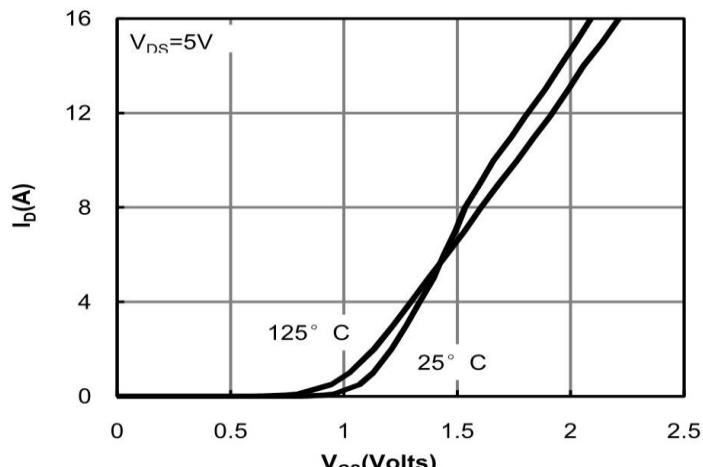


Figure 2: Transfer Characteristics

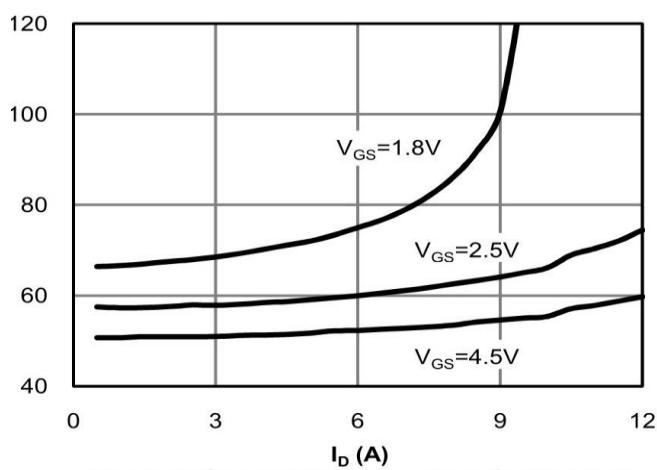


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

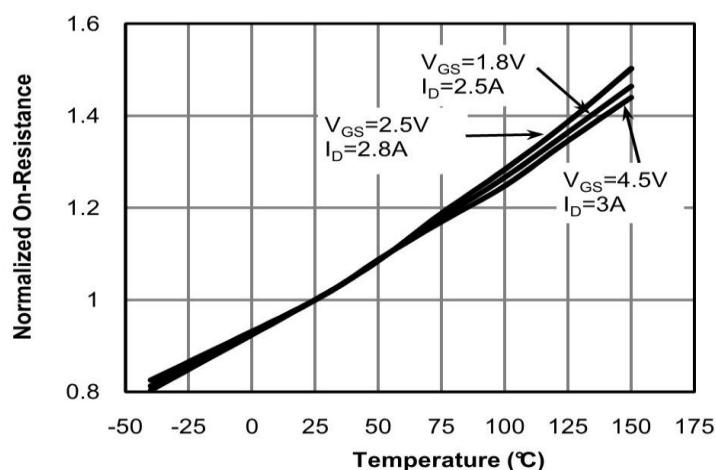
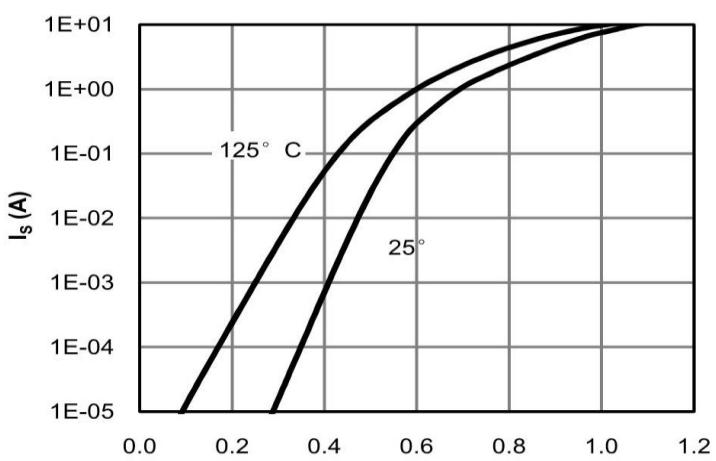
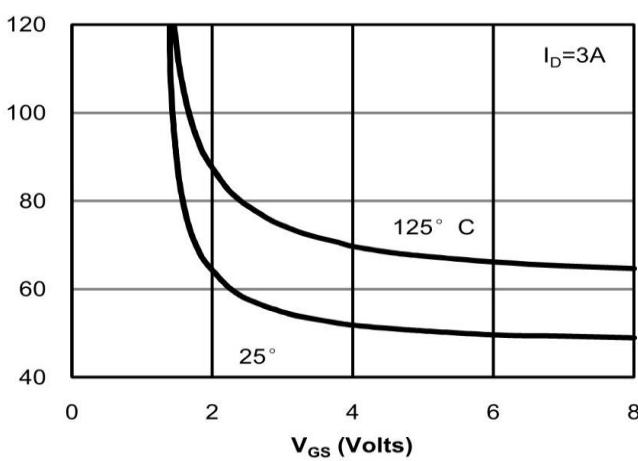


Figure 4: On-Resistance vs. Junction Temperature



ESSENTIAL ELECTRICAL AND THERMAL CHARACTERISTICS

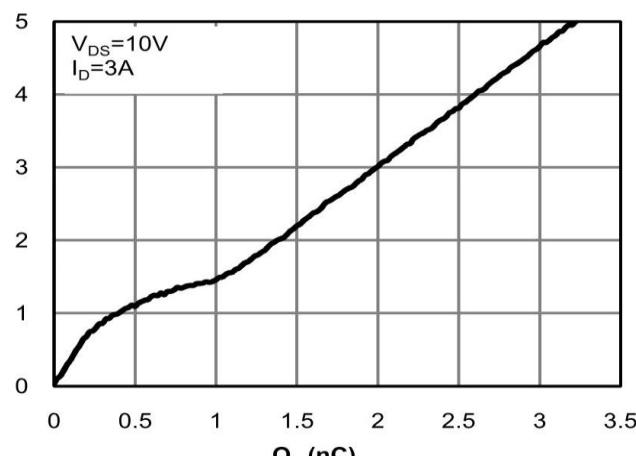


Figure 7: Gate-Charge Characteristics

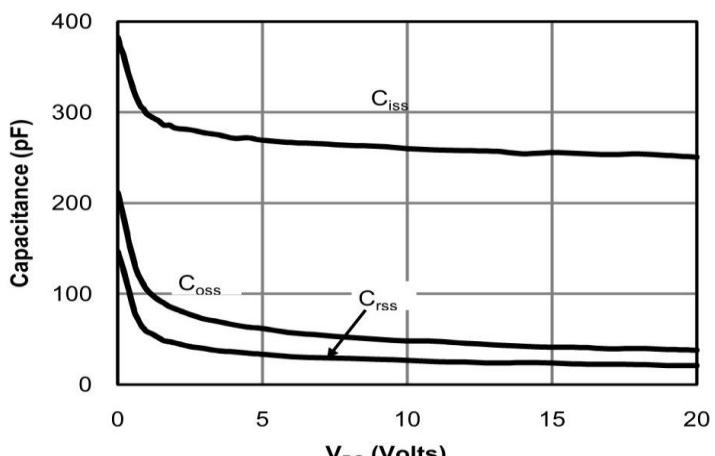


Figure 8: Capacitance Characteristics

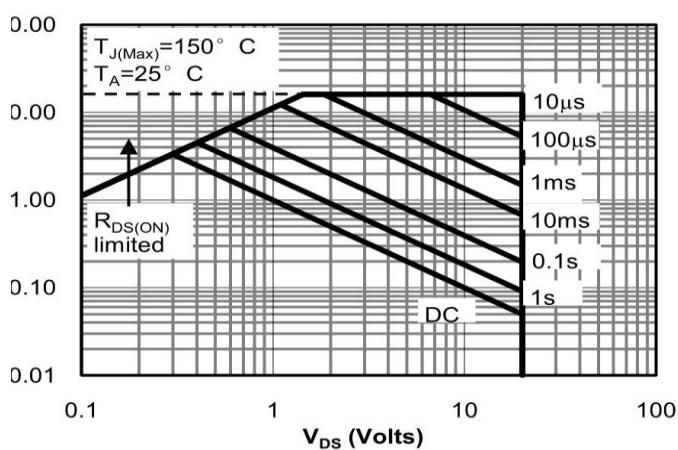


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

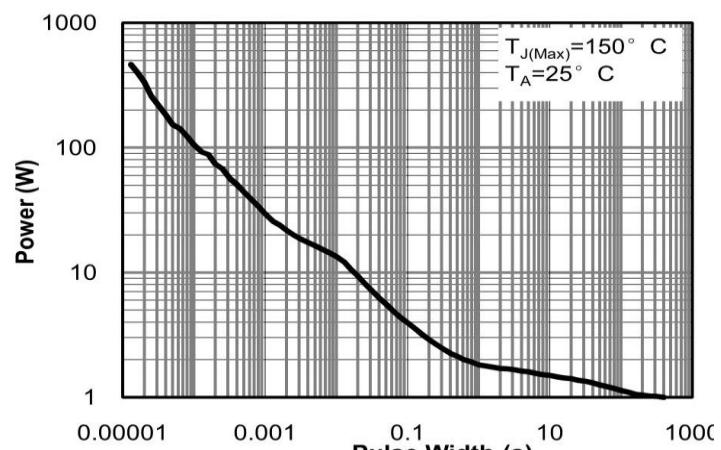


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

